

## P-Channel 20-V (D-S) MOSFET

### Key Features:

- Low  $r_{DS(on)}$  trench technology
- Low thermal impedance
- Fast switching speed

### Typical Applications:

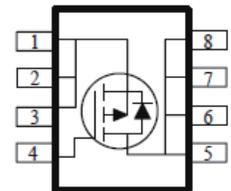
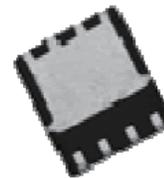
- Load Switches
- DC/DC Conversion
- Motor Drives

PRODUCT SUMMARY		
$V_{DS}$ (V)	$r_{DS(on)}$ (m $\Omega$ )	$I_D$ (A)
-20	7 @ $V_{GS} = -4.5V$	-18
	10 @ $V_{GS} = -2.5V$	-15



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

DFN3x3-8L



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	
Continuous Drain Current <sup>a</sup>	$I_D$	$T_A = 25^\circ\text{C}$	-18
		$T_A = 70^\circ\text{C}$	-14
Pulsed Drain Current <sup>b</sup>	$I_{DM}$	-70	
Continuous Source Current (Diode Conduction) <sup>a</sup>	$I_S$	-4.9	A
Power Dissipation <sup>a</sup>	$P_D$	$T_A = 25^\circ\text{C}$	3.5
		$T_A = 70^\circ\text{C}$	2
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Maximum	Units
Maximum Junction-to-Ambient <sup>a</sup>	$R_{\theta JA}$	$t \leq 10$ sec	35
		Steady State	81

### Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

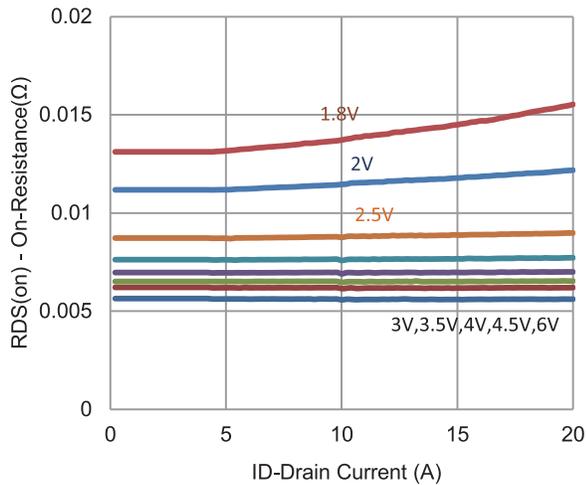
## Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static</b>						
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-0.5			V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 V, V_{GS} = \pm 12 V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -16 V, V_{GS} = 0 V$			-1	uA
		$V_{DS} = -16 V, V_{GS} = 0 V, T_J = 55^\circ C$			-10	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} = -5 V, V_{GS} = -4.5 V$	-30			A
Drain-Source On-Resistance <sup>a</sup>	$r_{DS(on)}$	$V_{GS} = -4.5 V, I_D = -14.6 A$			7	mΩ
		$V_{GS} = -2.5 V, I_D = -11.7 A$			10	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = -15 V, I_D = -14.6 A$		15		S
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = -2.5 A, V_{GS} = 0 V$		-0.69		V
<b>Dynamic <sup>b</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = -10 V, V_{GS} = -4.5 V,$ $I_D = -14.6 A$		90		nC
Gate-Source Charge	$Q_{gs}$			9.2		
Gate-Drain Charge	$Q_{gd}$			28		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = -10 V, R_L = 0.7 \Omega,$ $I_D = -14.6 A,$ $V_{GEN} = -4.5 V, R_{GEN} = 6 \Omega$		20		ns
Rise Time	$t_r$			43		
Turn-Off Delay Time	$t_{d(off)}$			238		
Fall Time	$t_f$			128		
Input Capacitance	$C_{iss}$	$V_{DS} = -15 V, V_{GS} = 0 V, f = 1 Mhz$		4665		pF
Output Capacitance	$C_{oss}$			646		
Reverse Transfer Capacitance	$C_{rss}$			608		

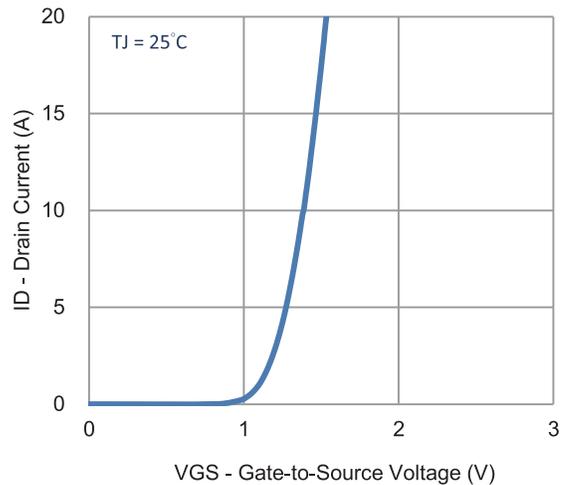
## Notes

- Pulse test: PW ≤ 300us duty cycle ≤ 2%.
- Guaranteed by design, not subject to production testing.

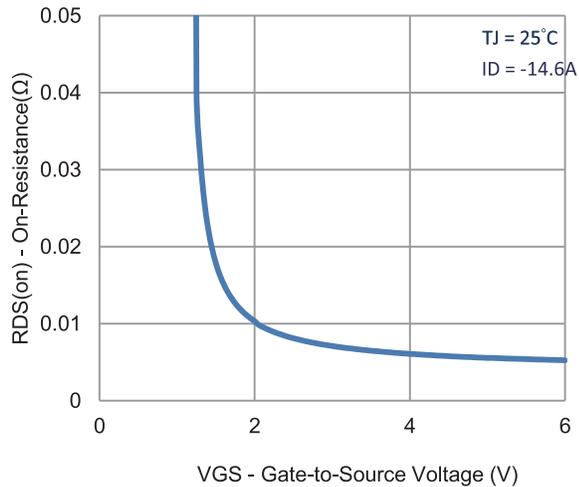
## Typical Electrical Characteristics



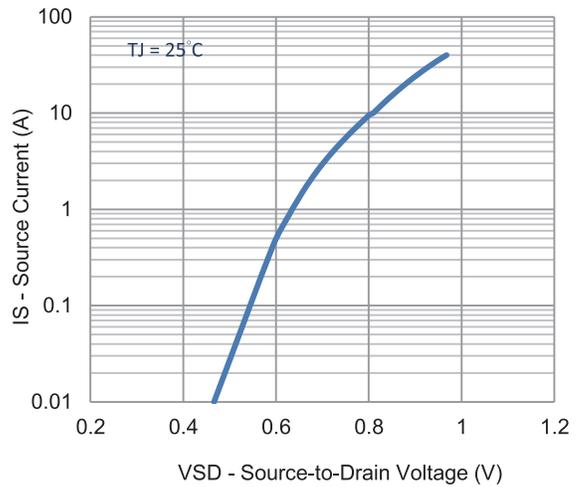
**1. On-Resistance vs. Drain Current**



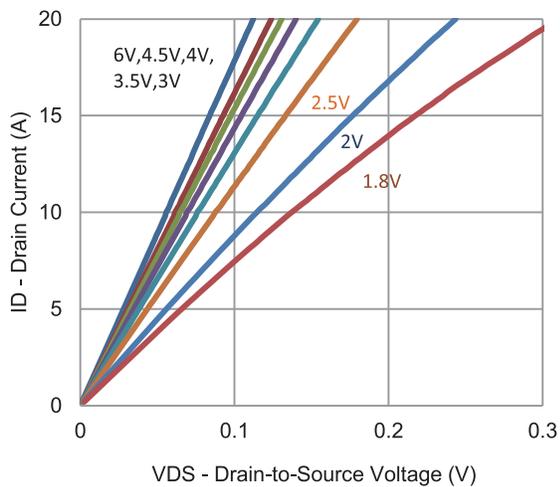
**2. Transfer Characteristics**



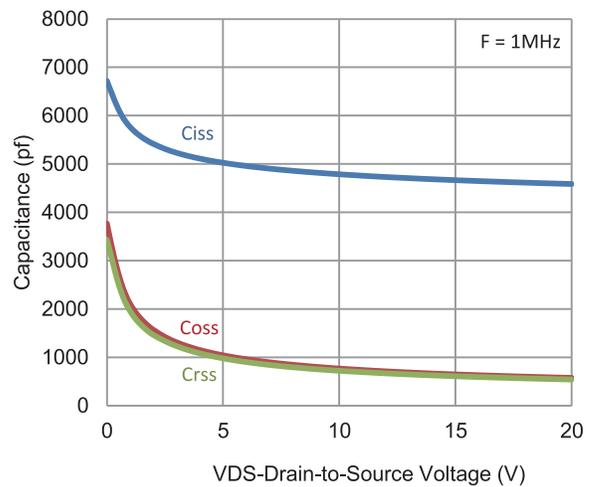
**3. On-Resistance vs. Gate-to-Source Voltage**



**4. Drain-to-Source Forward Voltage**

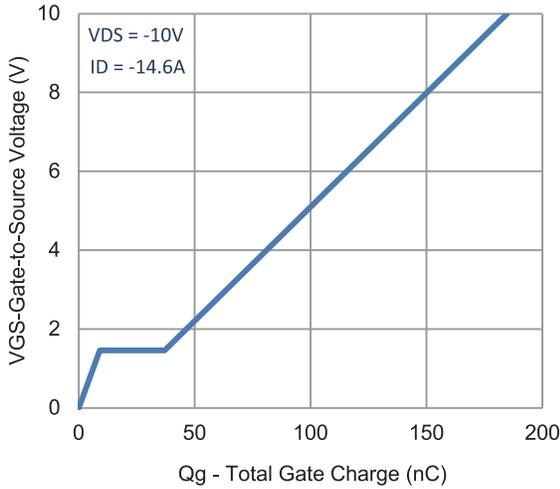


**5. Output Characteristics**

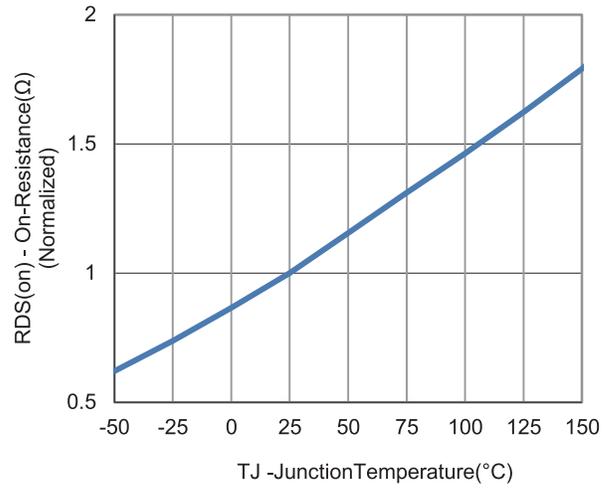


**6. Capacitance**

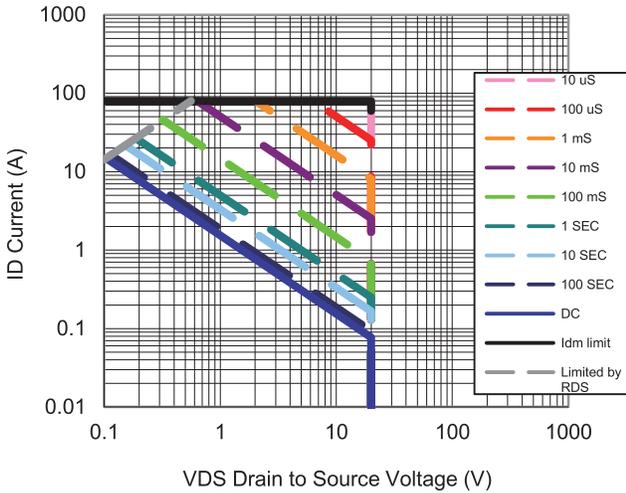
Typical Electrical Characteristics



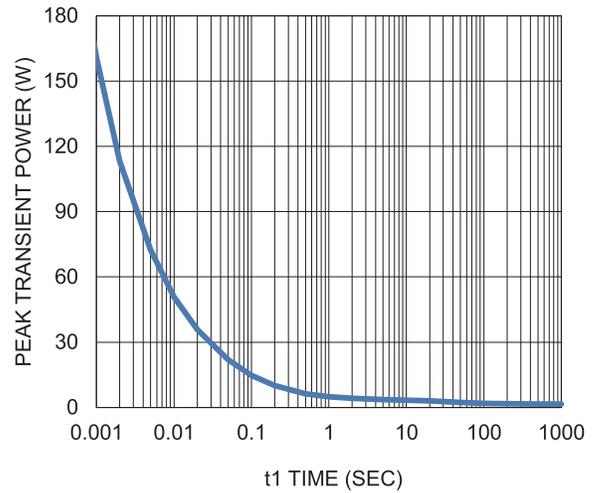
7. Gate Charge



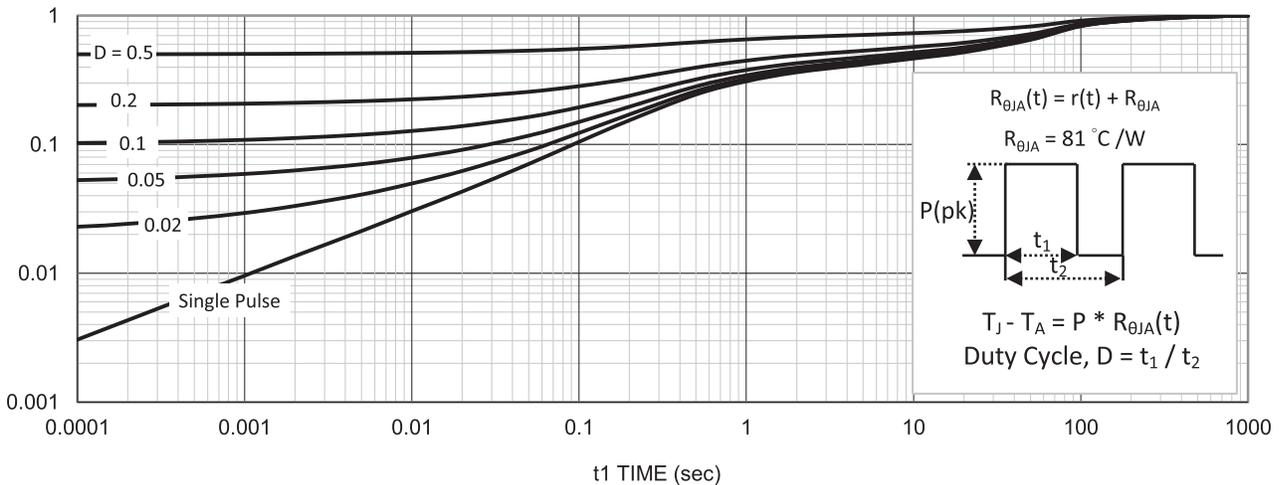
8. Normalized On-Resistance Vs Junction Temperature



9. Safe Operating Area

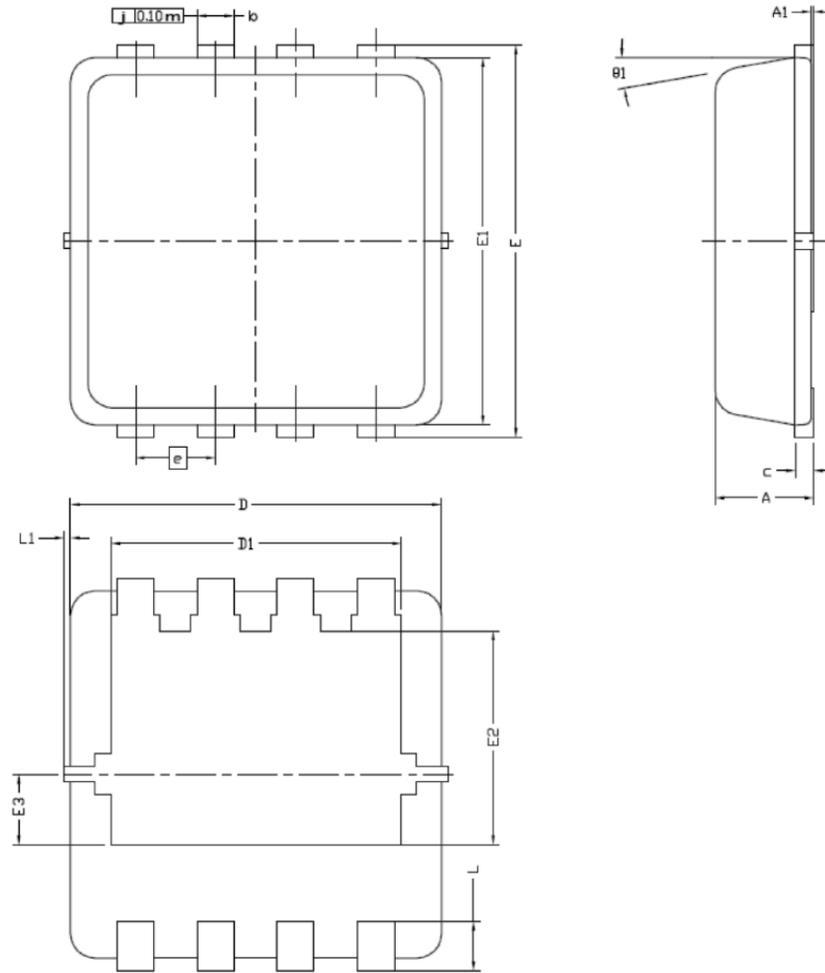


10. Single Pulse Maximum Power Dissipation



11. Normalized Thermal Transient Junction to Ambient

## Package Information



DIM.	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.700	0.80	0.900	0.0276	0.0315	0.0354
A1	0.00	---	0.05	0.000	---	0.002
b	0.24	0.30	0.35	0.009	0.012	0.014
c	0.10	0.152	0.25	0.004	0.006	0.010
D	3.00 BSC			0.118 BSC		
D1	2.35 BSC			0.093 BSC		
E	3.20 BSC			0.126 BSC		
E1	3.00 BSC			0.118 BSC		
E2	1.75 BSC			0.069 BSC		
E3	0.575 BSC			0.023 BSC		
e	0.65 BSC			0.026 BSC		
L	0.30	0.40	0.50	0.0118	0.0157	0.0197
L1	0	---	0.100	0	---	0.004
$\theta_1$	0°	10°	12°	0°	10°	12°